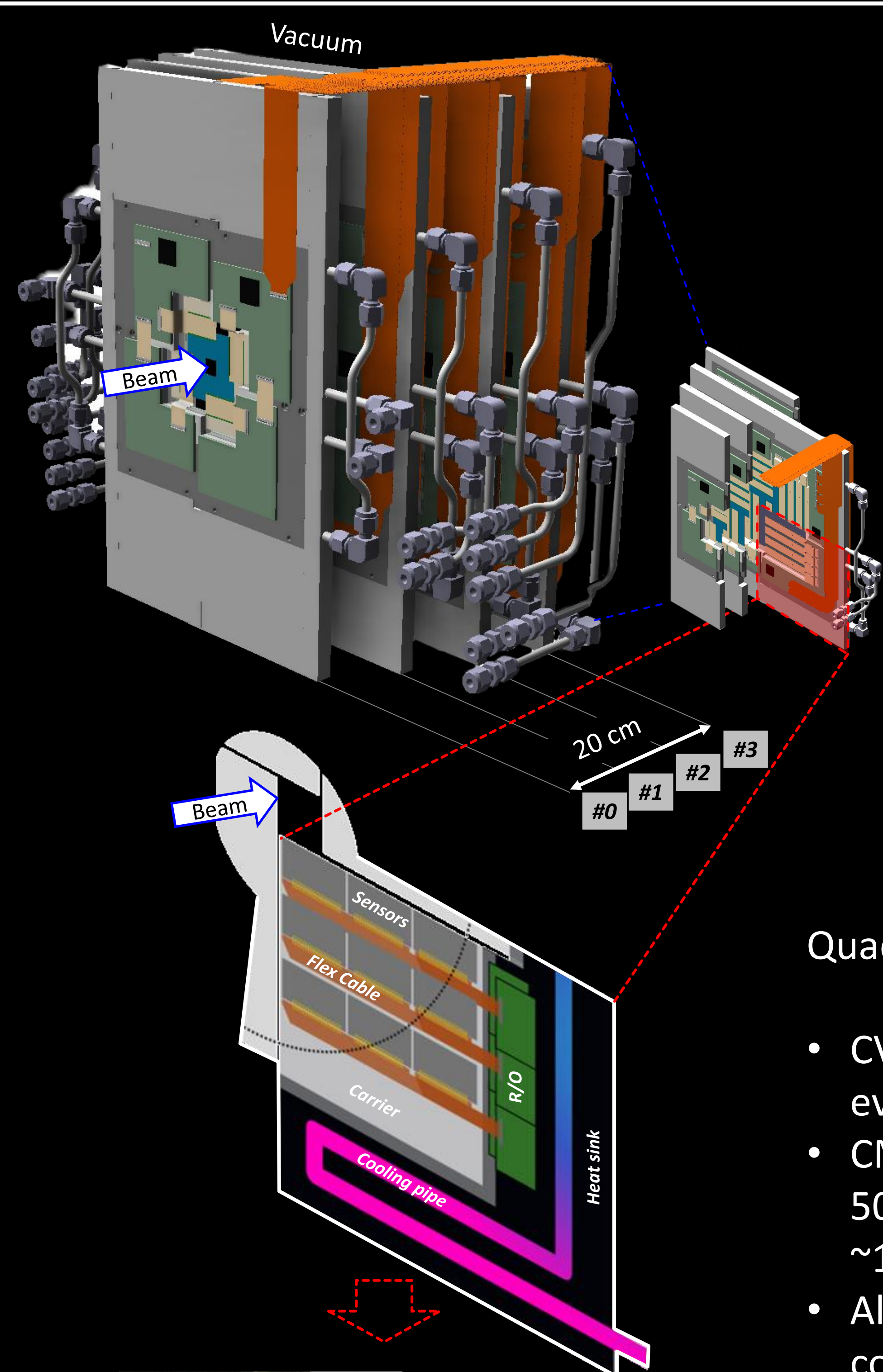


Vacuum-Compatible, Ultra-Low Material Budget Micro Vertex Detector of the Compressed Baryonic Matter Experiment at FAIR

14th Vienna Conference on Instrumentation, Vienna 2016.

Michal Koziel for the CBM-MVD collaboration

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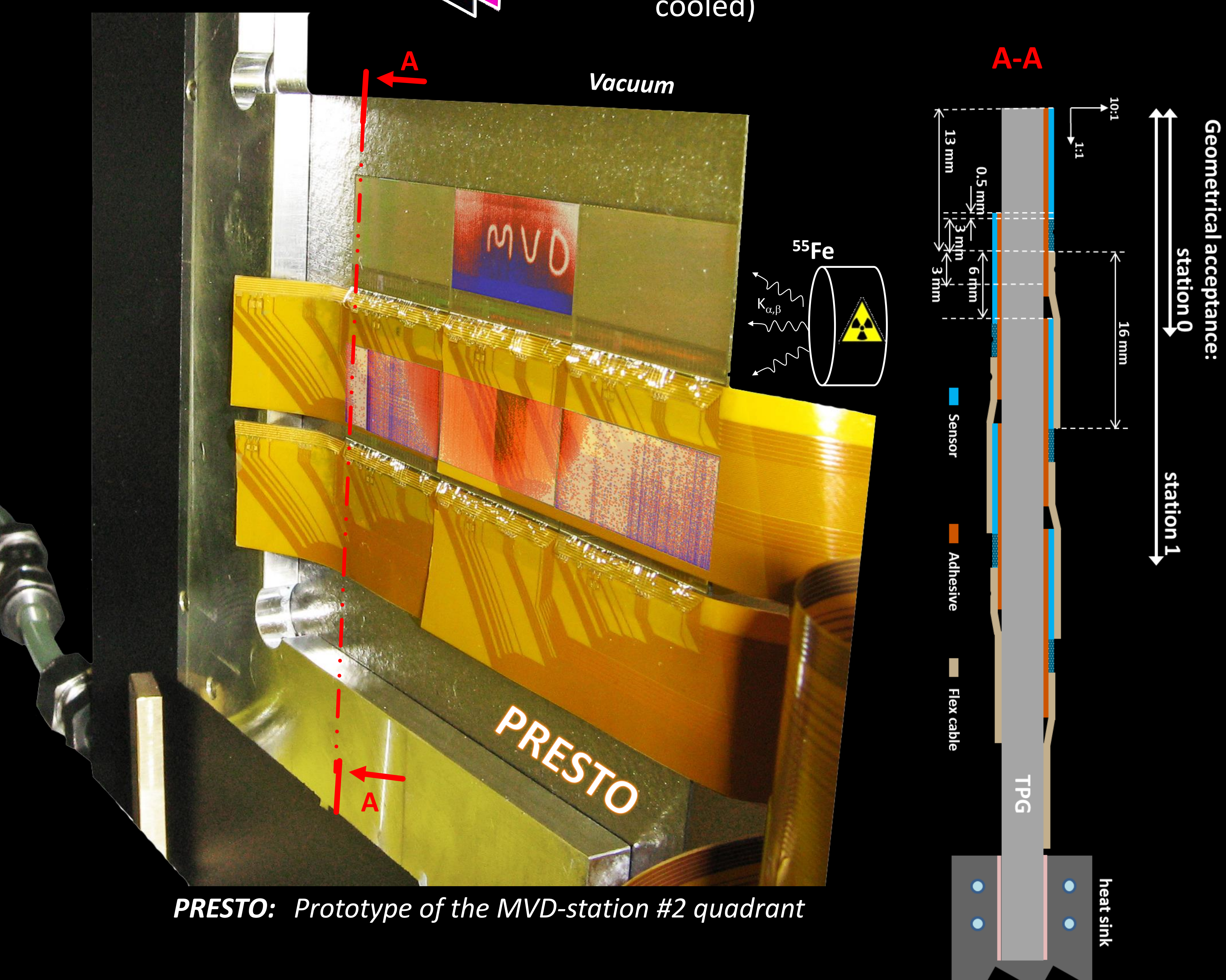


Micro Vertex Detector (MVD) for the CBM experiment at GSI/FAIR:

- Secondary vertex determination (10 μm scale), background rejection in di-electron spectroscopy, reconstruction of weak decays
- Vacuum/magnetic field operation
- 4 stations at 5, 10, 15 & 20 cm downstream the target
- ~300 CMOS sensors
- Power dissipation: 150 W
- Radiation tolerance: $>10^{13} n_{\text{eq}}/\text{cm}^2$ & $>1 \text{ Mrad}$

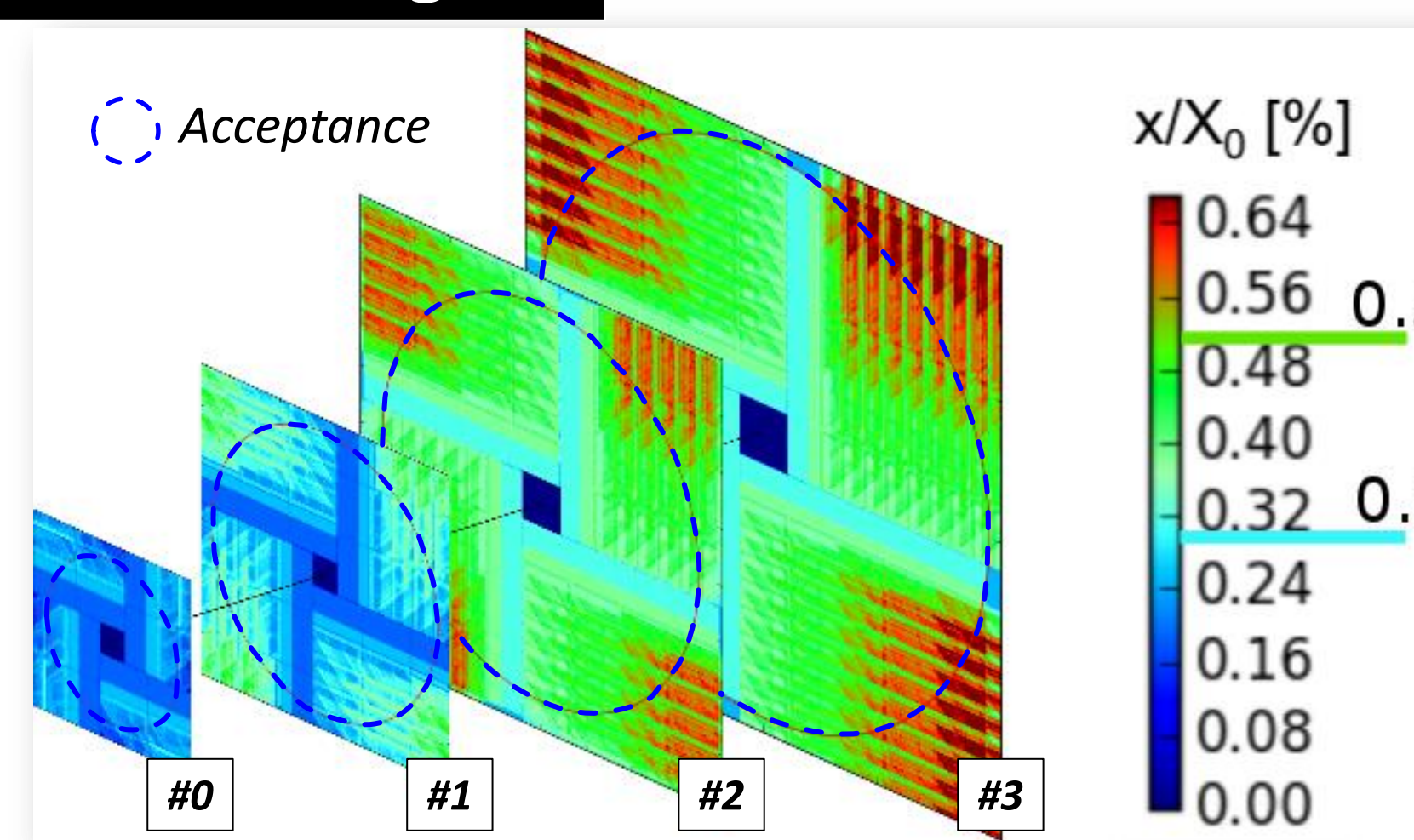
Quadrant (smallest functional unit):

- CVD Diamond / TPG carrier for heat evacuation
- CMOS pixel sensors: 50 μm thin, 150 mW/cm², ~10 μs read-out
- Aluminum heat-sink (actively cooled)



PRESTO: Prototype of the MVD-station #2 quadrant

Material Budget



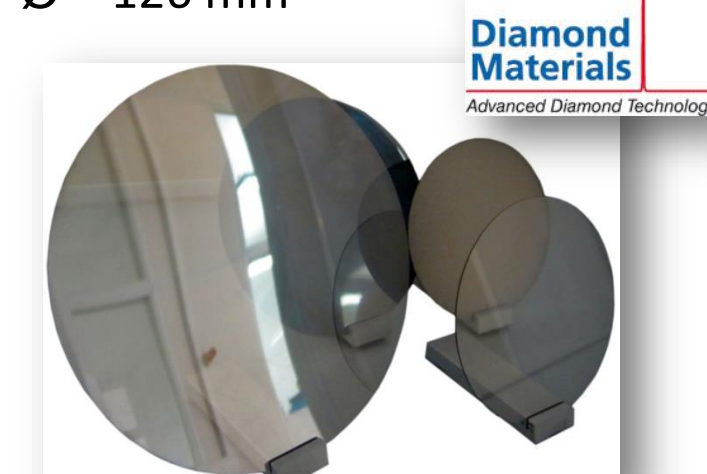
Targeted values for stations

2 & 3

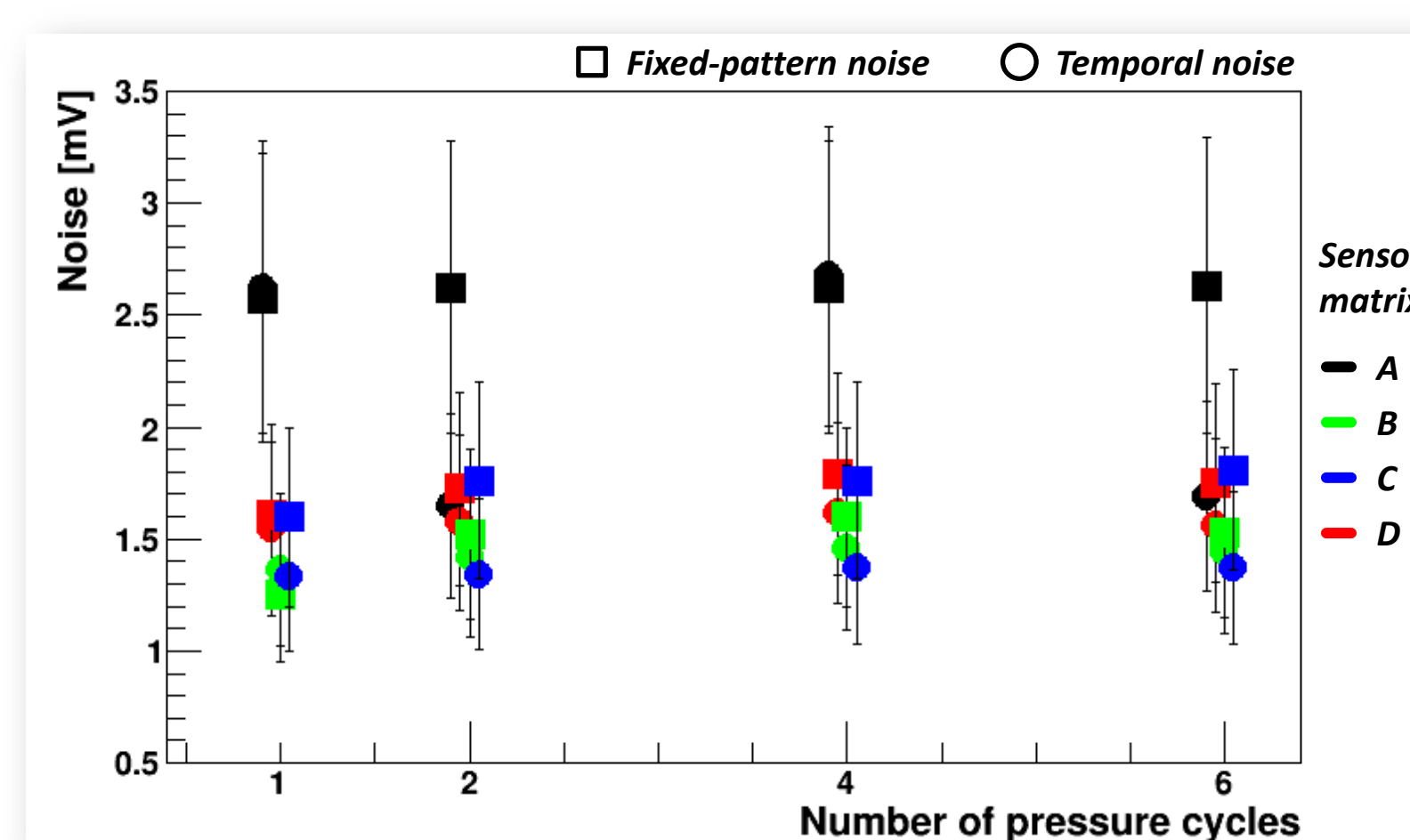
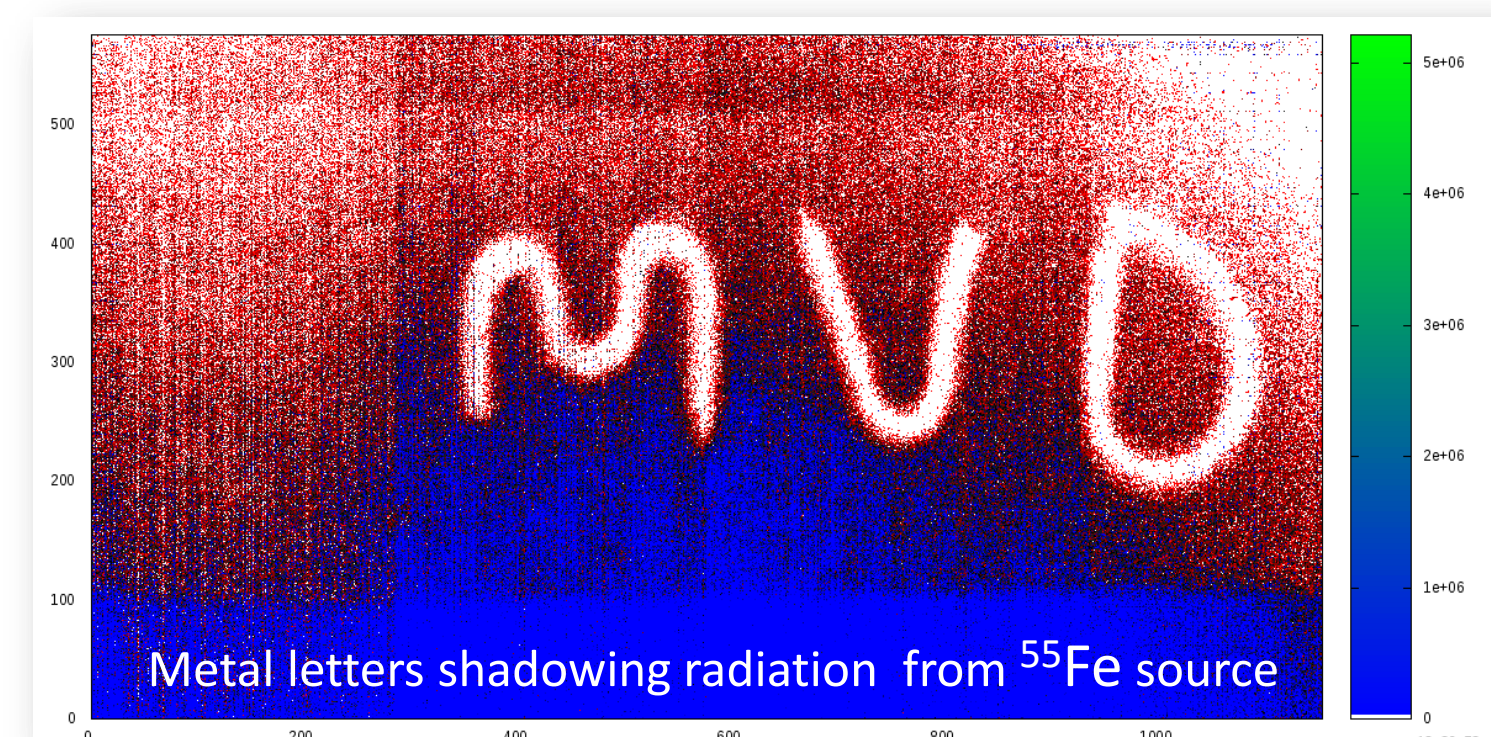
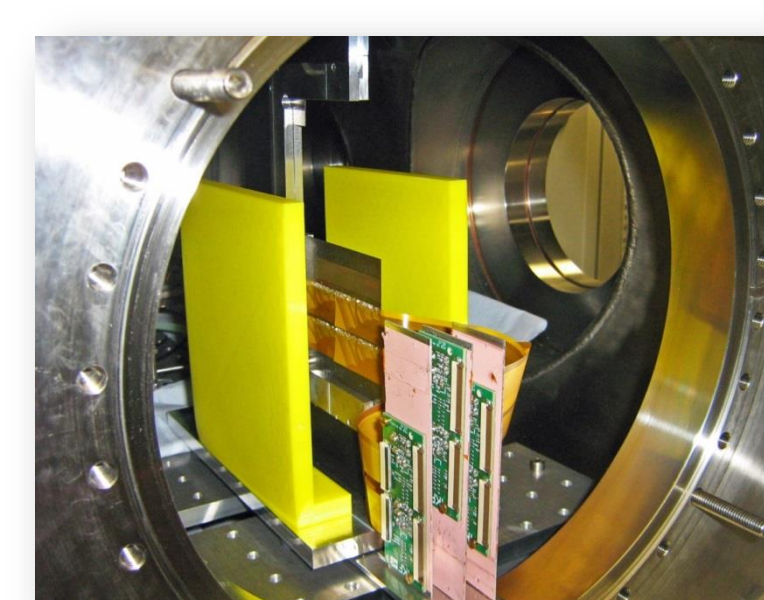
0 & 1

Component	Thickness [mm]	x/X_0 [%]
Sensor (MIMOSA-26)	0.05	0.053
Glue	0.03	0.009
TPG carrier (# 2&3)	0.38	0.200
CVD diamond carrier (# 0&1)	0.15	0.123
Flex cable (Cu traces)	0.063	0.051

CVD diamond thickness = 150 μm
 $\varnothing = 126 \text{ mm}$



Vacuum Compatibility



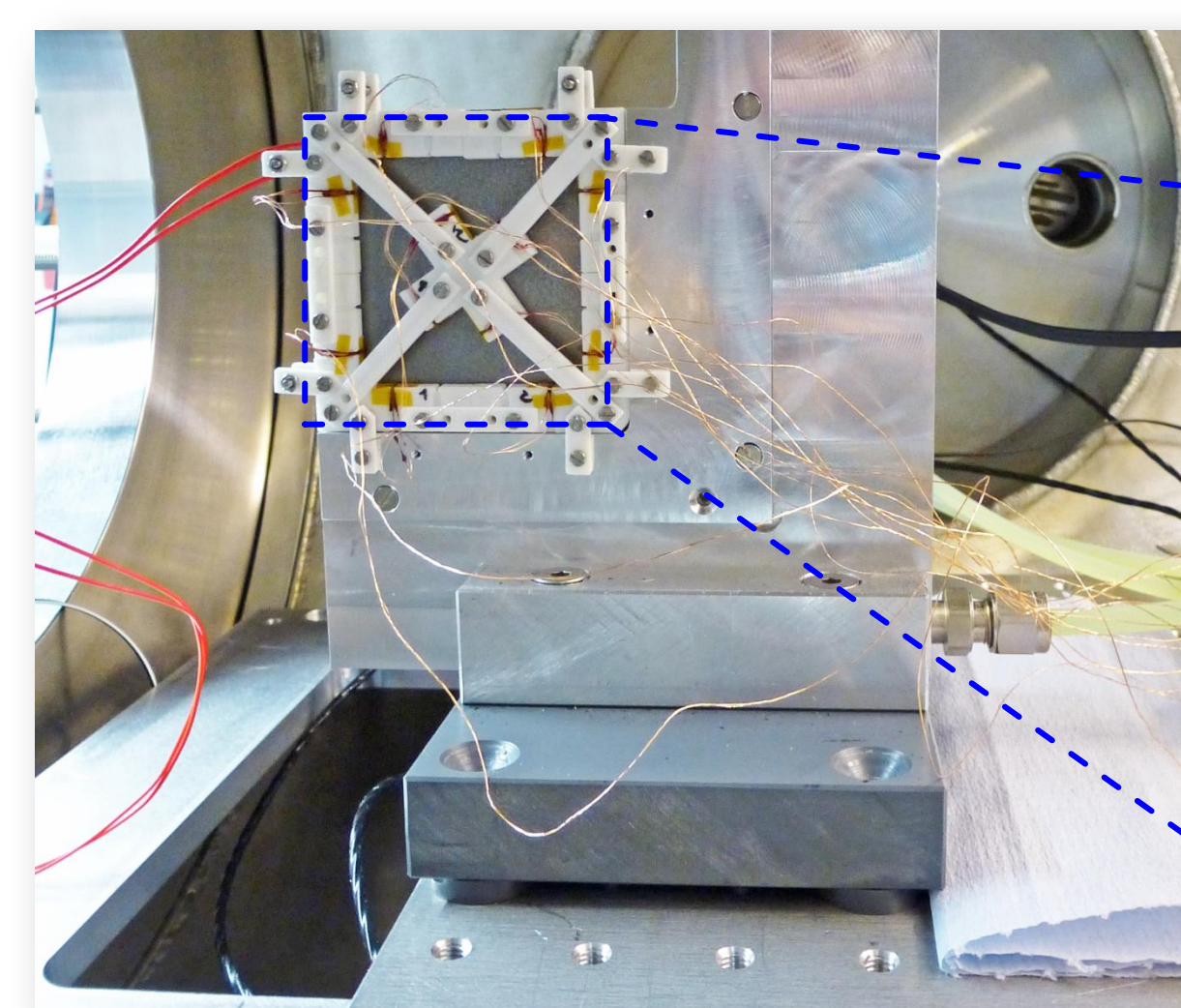
- Pressure: 10^{-3} mbar
- Temperature: $+13 \text{ }^\circ\text{C}$ at the heat sink
- Acquisition time: 10 min

No performance loss observed after several pressure cycles

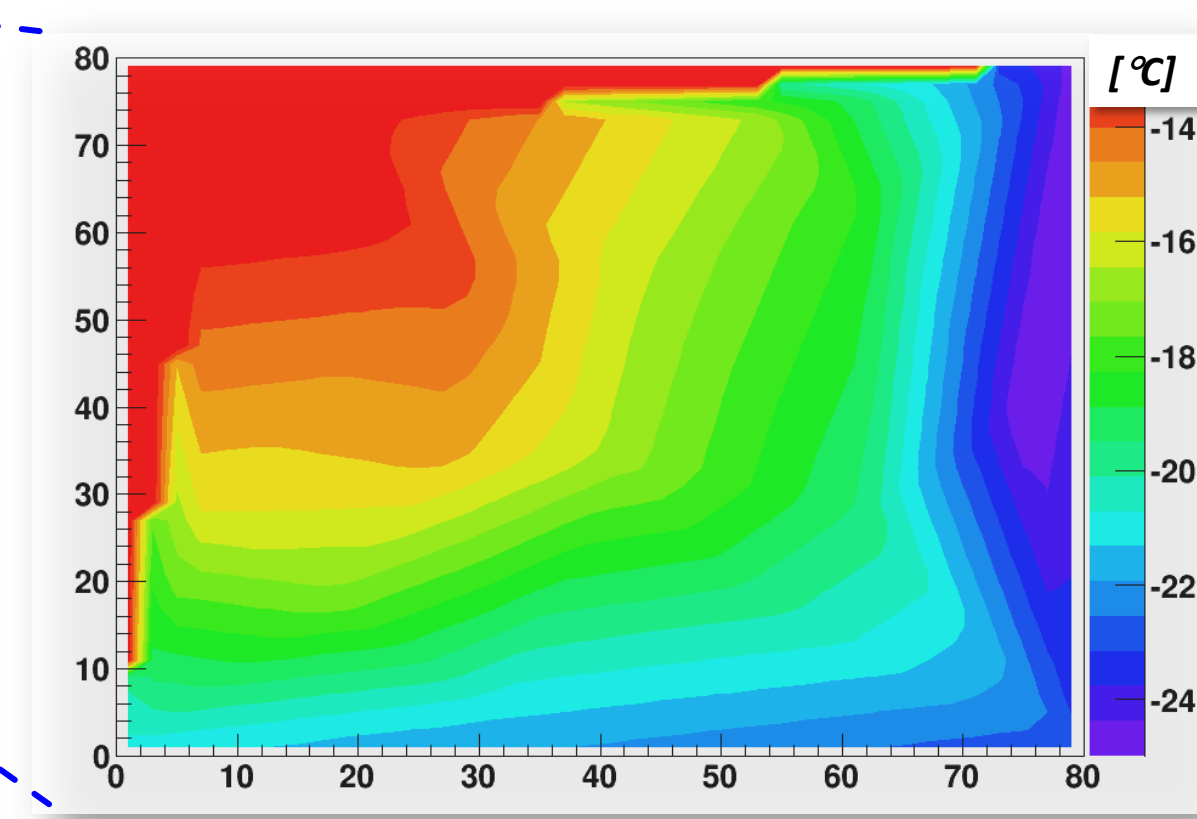
Heat Evacuation in Vacuum

- TPG support **MOMENTIVE**
- Thickness: 500 μm
 - Conductivity: 1500 W/mK
 - x/X_0 : 0.262 %

- Cooling liquid: $-40 \text{ }^\circ\text{C}$
- Heat source: Flexible Kapton heaters from **OMEGA**



- Power dissipation: 15.5 W

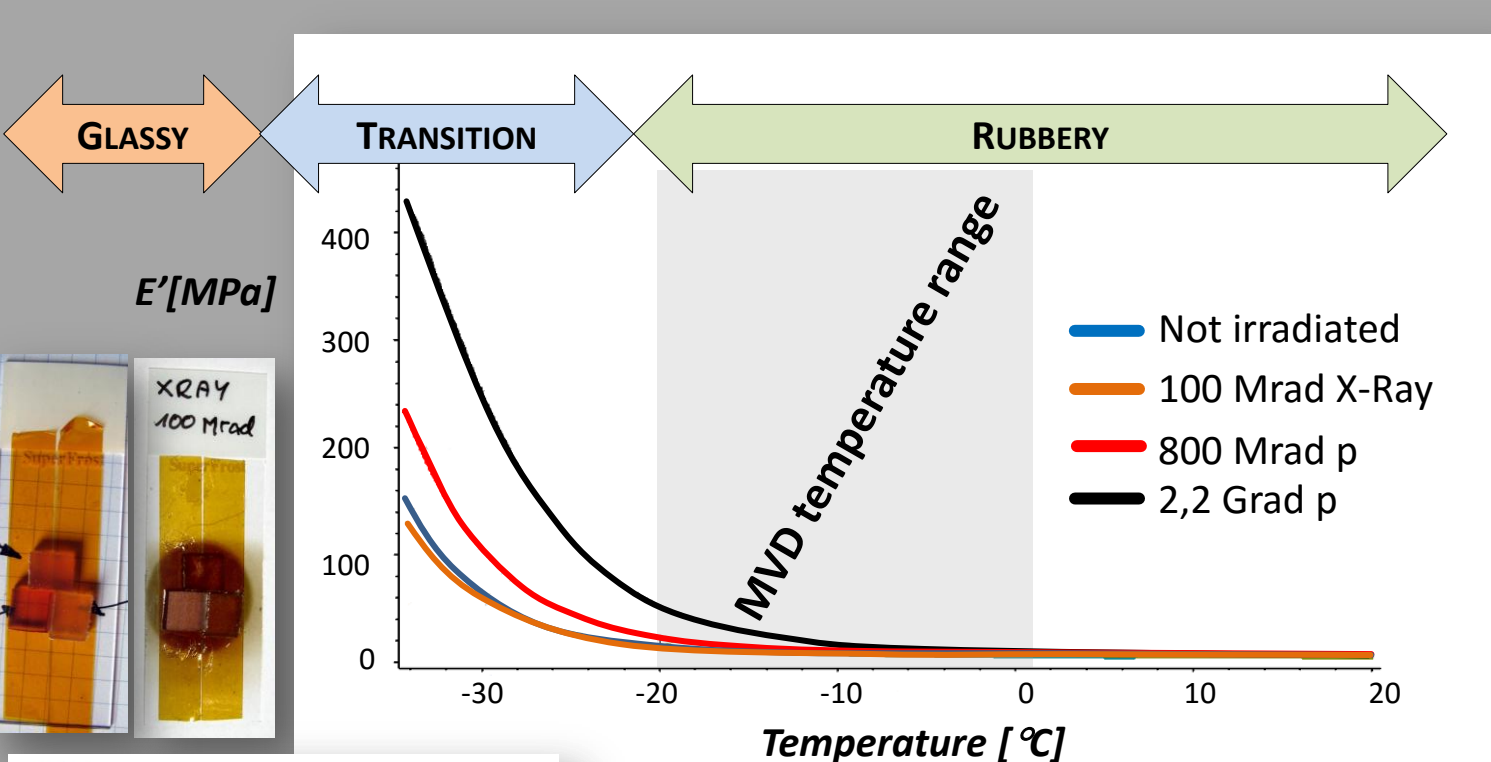


Integration Aspects

Custom-made adhesive

RAL-247 features:

- Glass temperature (T_g) @ $-45 \text{ }^\circ\text{C}$
- Viscosity of below 100 mPa·s
- Curing time 48h @ $+50 \text{ }^\circ\text{C}$ and more than a week at $20 \text{ }^\circ\text{C}$

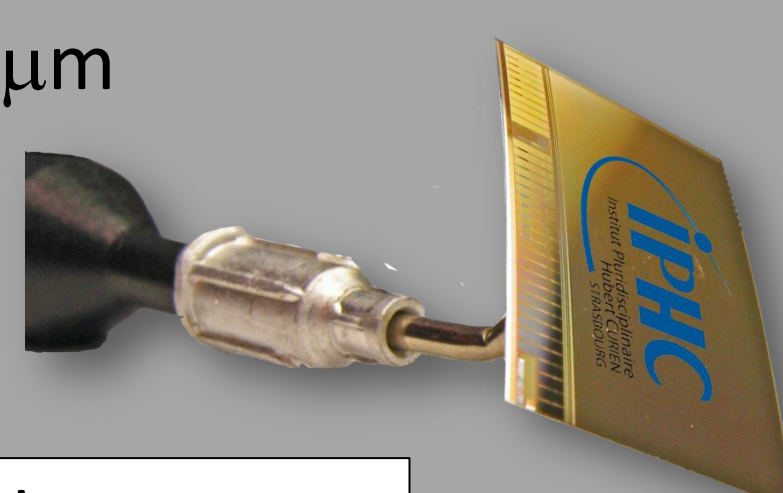


Science & Technology Facilities Council Rutherford Appleton Laboratory Synergy with the ATLAS experiment

Supported by HIC for FAIR, EU, BMBF and GSI.

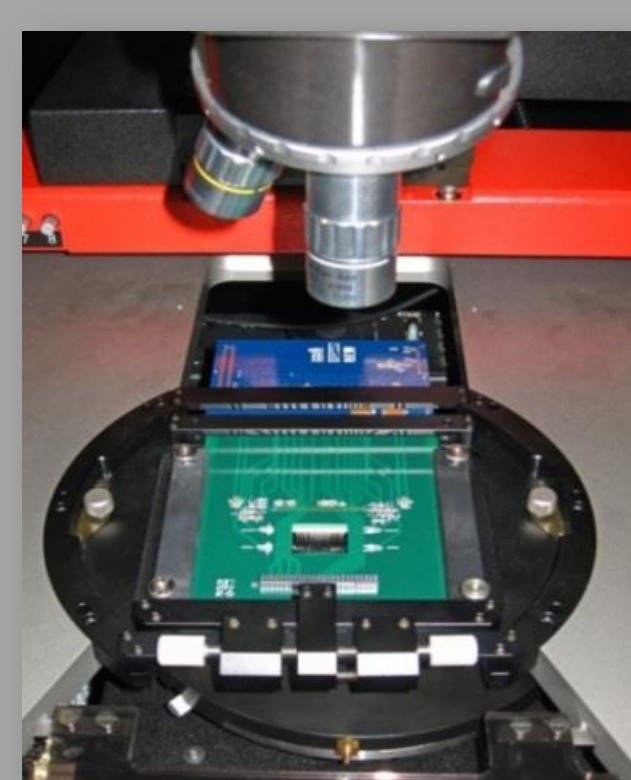
Sensor

Family: CMOS pixel sensor
Process: AMS CMOS 0.35 μm
Model: MIMOSA-26
Thickness: 50 μm



Sensor probe tests

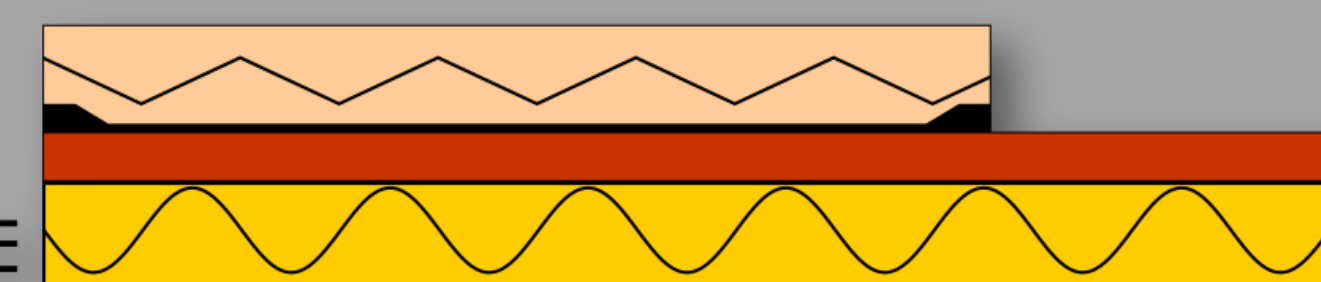
- 65 standard tungsten needles
- Dedicated chuck adapter for holding 50- μm thin sensors
- No cooling
- Sensor yield ~67 %
- QA for other applications (PLUME, NA-61)



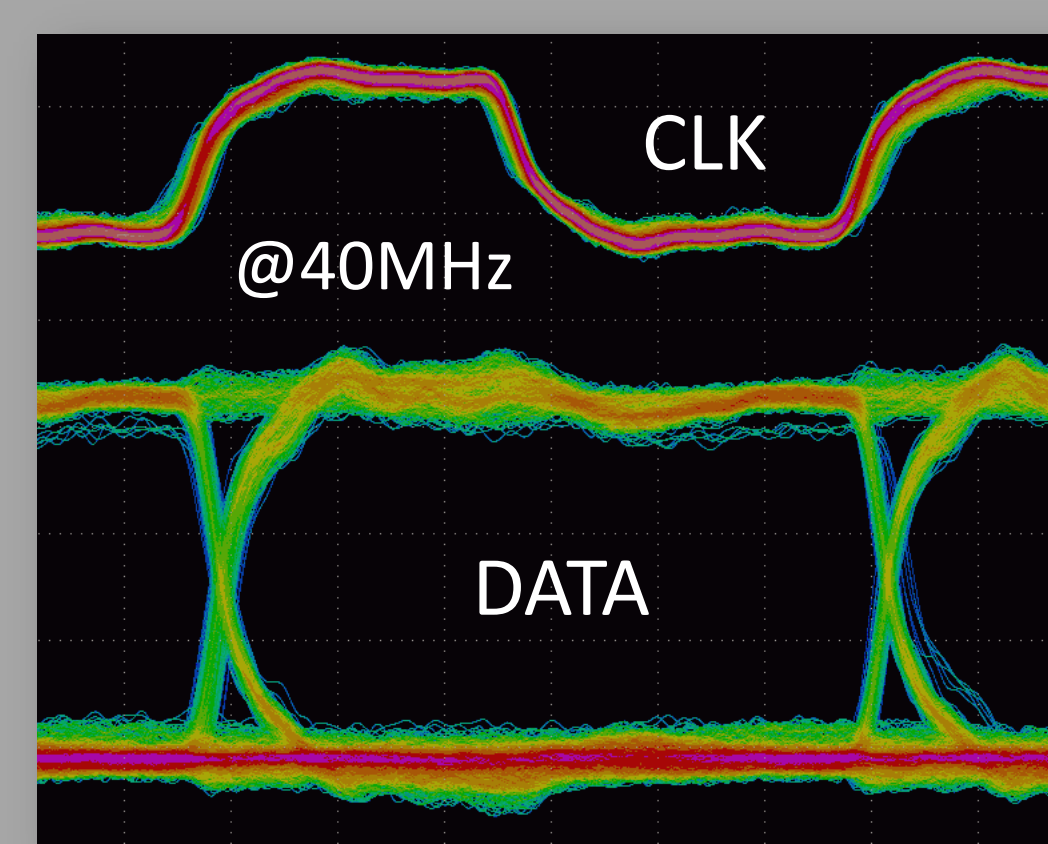
Flex cable

$x/X_0 \approx 0.051 \%$

26 μm Coverlay FR7001
12 μm Copper
25 μm Polyimide AP7164E



- Industry standard
- Single layer
- Cu-based
- Material-budget oriented
- ~30 cm long



- No sensor-to-sensor influence during read-out and power cycling
- Locally, material budget of the TPG-based MVD stations is slightly above an accepted limit \rightarrow improvement by changing Cu to Al traces